

ANSYS Power Noise And Reliability Solutions Adopted By Fujitsu For High-Performance Processor Designs

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PITTSBURGH, Jan. 13, 2015 /PRNewswire/ -- <u>ANSYS</u> (NASDAQ: ANSS) announced today that Fujitsu Limited is using its power noise and reliability solutions to create three-dimensional integrated circuits to meet performance requirements for next-generation high-performance central processing units.



These chips leverage three-dimensional integrated circuit (3D-IC) architecture to gain power, performance and price advantages, but the configuration increases the design complexity and the challenges associated with power and thermal management. ANSYS®RedHawk™ and ANSYS®Sentinel™ provide Fujitsu with the ability to perform IR (voltage) drop, electromigration (EM) and thermal reliability analysis of its large processor designs by delivering full-chip capacity, fast turnaround time and production-proven sign-off accuracy.

Finding the optimal floor plan for 3D-IC requires placement of through-silicon-via (TSV), as well as the power/ground network. This added complexity necessitates early-stage floor planning, analysis and debugging, as power and thermal issues become difficult to resolve later in the design process. Using RedHawk, Fujitsu can explore various TSV placement options to meet chips' power noise and reliability requirements.

"The use of 3D-IC architecture adds complexity that needs to be addressed early in the design process," said Tatsumi Nakada, Director, Next Generation LSI Packaging Development Office at Fujitsu Limited. "By using RedHawk and Sentinel, we are able to optimize our design to meet power, performance and chip cost targets."

"Industry-leading companies such as Fujitsu need to continuously push the envelope to meet their customers' needs," said Fares Mubarak, ANSYS vice president and general manager. "ANSYS is committed to delivering best-in-class solutions that address our customers' growing power noise and reliability challenges."

About ANSYS, Inc.

ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs over 2700 professionals, many of them expert in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, embedded software, system simulation and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

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